## MATERIAL DECLARATION SHEET

<table>
<thead>
<tr>
<th>Material Number</th>
<th>BSDD05G120E2 TO252</th>
</tr>
</thead>
<tbody>
<tr>
<td>Product Line</td>
<td>Semiconductor</td>
</tr>
<tr>
<td>Compliance Date</td>
<td>2023-05-22</td>
</tr>
<tr>
<td>RoHS Compliant</td>
<td>YES</td>
</tr>
<tr>
<td>MSL</td>
<td>1</td>
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</table>

<table>
<thead>
<tr>
<th>No.</th>
<th>Construction Element(subpart)</th>
<th>Homogeneous Material</th>
<th>Material weight [mg]</th>
<th>Homogeneous Material\Substances</th>
<th>CASRN if applicable</th>
<th>Materials Mass %</th>
<th>Material Mass % of total unit wt.</th>
<th>Subpart mass of total wt. (%)</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Die</td>
<td>Silicon Carbide</td>
<td>1.42</td>
<td>Silicon Carbide (SiC)</td>
<td>409-21-2</td>
<td>100</td>
<td>0.312</td>
<td>0.312</td>
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<tr>
<td>2</td>
<td>Die Attach</td>
<td>Die Attach</td>
<td>0.02</td>
<td>Diethylene Glycol Monoethyl Ether Acetate</td>
<td>112-15-2</td>
<td>5</td>
<td>0.004</td>
<td>0.081</td>
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<tr>
<td></td>
<td></td>
<td></td>
<td>0.35</td>
<td>Silver (Ag)</td>
<td>7440-22-4</td>
<td>95</td>
<td>0.077</td>
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<tr>
<td>3</td>
<td>Lead Frame</td>
<td>Copper alloy</td>
<td>0.05</td>
<td>Phosphorous (P)</td>
<td>7723-14-0</td>
<td>0.03</td>
<td>0.011</td>
<td>38.324</td>
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<td></td>
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<td>0.05</td>
<td>Nickel (Ni)</td>
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<td>0.011</td>
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<td>0.17</td>
<td>Iron (Fe)</td>
<td>7439-89-6</td>
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<td>173.92</td>
<td>Copper (Cu)</td>
<td>7440-50-8</td>
<td>99.84</td>
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<td>4</td>
<td>Mold Compound</td>
<td>Resin</td>
<td>10.09</td>
<td>Phenol Formaldehyde resin (generic)</td>
<td>9003-35-4</td>
<td>3.8</td>
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<td>58.431</td>
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<td></td>
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<td>15.93</td>
<td>Epichlorohydrid/Diethyleneglycol Epoxy resin (generic)</td>
<td>25928-94-3</td>
<td>6</td>
<td>3.505</td>
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<td></td>
<td>239.02</td>
<td>Silica fused</td>
<td>60676-86-0</td>
<td>90</td>
<td>52.589</td>
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<td>0.53</td>
<td>Carbon black</td>
<td>1333-86-4</td>
<td>0.2</td>
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<td>5</td>
<td>Plating</td>
<td>Tin plating</td>
<td>12</td>
<td>Tin (Sn)</td>
<td>7440-31-5</td>
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<tr>
<td>6</td>
<td>Wire</td>
<td>Pure metal</td>
<td>0.96</td>
<td>Aluminium (Al)</td>
<td>7429-90-5</td>
<td>100</td>
<td>0.211</td>
<td>0.211</td>
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</tbody>
</table>

Total weight 454.51 mg

**This Document was updated on:** 2023/05/22

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements